

L Number	Hits	Search Text	DB	Time stamp
1	2469080	semiconductor die dice chip ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 12:57
2	4419983	stack stacking stacked above oppose	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 12:58
3	225209	(semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 12:59
4	34846	package and ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:01
5	30728	(polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:01
6	7575	package and ((polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:01
7	4980	pad and (package and ((polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:02
8	3850	wires and (pad and (package and ((polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:10
9	3086	(sealing encapsulant epoxy) and (wires and (pad and (package and ((polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:10
10	2906	(substrate carrier board pcb) and ((sealing encapsulant epoxy) and (wires and (pad and (package and ((polyimide polyimide elastic liquid tape nonconductive (non adj conductive) adhesive adhesion insulator insulative spacer) same ((semiconductor die dice chip ic (integrated adj circuit)) with (stack stacking stacked above oppose))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:12